These assemblies are ESD sensitive, ESD precautions shall be observed.
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
Place SH-J2 on J2, SH-J11 on J11.

COMMENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE

<table>
<thead>
<tr>
<th>BOARD #</th>
<th>REV</th>
<th>SUN REV</th>
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<td>ISE4040</td>
<td>E2</td>
<td>Not In VersionControl</td>
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TID #: TIDA-00380

PLOT NAME = Top Assembly Drawing

GENERATED: 9/22/2015 10:23:15 AM

TEXAS INSTRUMENTS
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